

2nd Executive Infrared Imaging Forum

UNCOOLED INFRARED IMAGING FOR VOLUME APPLICATIONS

September 7th, 2017
Shenzhen, China

SAVE
THE DATE

Alongside China International
Optoelectronic Expo

Organized by
YOLE
Développement

Hosted by
CIOE
CHINA INTERNATIONAL
OPTOELECTRONIC
EXPO

CALL FOR PAPER

About the 2nd Executive Infrared Imaging Forum: Uncooled Infrared Imaging for Volume Applications

The 2nd Executive Infrared Imaging Forum organized by Yole Développement and hosted by CIOE will take place on September 7, 2017 in Shenzhen, alongside the 19th China International Optoelectronic Expo 2017. The event presents applications and technologies within the infrared imaging industry.

The forum will bring together a world-class panel of users and application experts and allow participants to get valuable insights into the status and future of the infrared imaging industry as well as provide unprecedented opportunities for meeting with industry leaders.

Sessions will focus on the following applications:

Surveillance-Thermography-Automotive-Consumer-Safety

Highlights from the 1st Executive Infrared Imaging Forum:

- 90+ delegates from Dali, Veeco, Sony, Ophir, Honeywell, i3system, Fluke, Flir, Melexis, Oxford Instruments Plasma,...
- 1 Privileged Exclusive Sponsor – Ulis
- 3+ hours of networking
- 10 Speakers from Heimann Sensor, Robert Bosch, Umicore, KAIST, Device Alab, Autoliv, Telops, Ulis, INO, Mikrosens.
- 2 Keynotes from Yole Développement and Heimann Sensor

Yole Développement and CIOE welcome original submissions in the following range of areas:

- | | |
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| <ul style="list-style-type: none">○ Applications:- Surveillance- Thermography- Automotive- Consumer & Personal Vision Systems- Safety & firefighting- Military- ... | <ul style="list-style-type: none">○ New technologies:- Active & passive detection- Integration and miniaturization,- Sensor fusion,- IR optics & lenses,- Packaging,- Imaging technologies (micro bolometer, thermopile, pyroelectric, CMOS ...),- Camera module,- Camera architecture,- ... |
|---|--|

- **New functions:**
 - Biometry,
 - Night vision,
 - Motions sensing,
 - People counting,
 - Spot thermometry,
 - Gesture recognition
 - ...
- **Manufacturing processes, materials and equipment:**
 - Silicon as an optical material, Chalcogenides, Ge ...
 - Wafer level packaging,
 - Wafer level optics,
 - Wafer level testing,
 - New detection material,
 - New manufacturing processes,
 - Roadmapping
 - Functional test,
 - ...

Please submit abstract (200 words max.) to Clotilde Fabre (fabre@yole.fr) by **April 24, 2017**. Your abstract can include one or two illustrations (graph, images...). If need assistance, please contact Shirly Yi, shirly.yi@cioe.cn.

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GUIDELINES FOR PAPER SUBMISSION

Papers must be original material and not have been previously presented or published.

- **Content:** technology and/or market focused content with in-depth information and analysis. The quality of the description of your presentation matters. The ability of your description to clearly explain what the attendees will take away from your presentation is critical for your submission to make it through the review process. The abstract must clearly describe the nature, scope, content, organization, key points and significance of the proposed paper.
- **Speaker:** please include short biography to the submitted paper.
- **Language:** all papers will be in English. Nevertheless, the conference presentation language can be Chinese as we organize a translation service
- **Procedure:** only papers submitted within the call for paper period will be accepted.
- **Exclusivity:** the paper may not be used for another conference in parallel, prior to the forum. It will be then sent to the attendees only.
- **Commercial aspect:** no commercial papers will be accepted. The presentation will not include direct or hidden product ads. In the presentation, only one slide is dedicated to company introduction. Product brand names may be mentioned infrequently if necessary for explanations.

- **Speaker benefits:** 1 free entrance per company to the forum, announcement with abstract, CV and photo on forum webpage and program, presentation sending to all attendees, announcement in the forum promotion.

IMPORTANT DATES

Please make sure the following deadlines and dates are respected:

- **Call for Paper opens: April 3rd, 2017**
- **Abstract due: April 24, 2017**
- **Author notification sent: April 28, 2017**
- **Speaker letter agreement due: May 30, 2017**
- **PowerPoint presentation due: August 18, 2017**

More information on please contact Clotilde Fabre (fabre@yole.fr)